



Material Content Data Sheet



Sales Product Name		1EDI20I12AF		Issued		20. July 2018		
MA#		MA001245998						
Package		PG-DSO-8-51		Weight*		80.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.151	2.68	2.68	26757	26757
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		103	
	non noble metal	zinc	7440-66-6	0.033	0.04		410	
	non noble metal	iron	7439-89-6	0.660	0.82		8208	
wire	non noble metal	copper	7440-50-8	26.789	33.33	34.20	333283	342004
	noble metal	gold	7440-57-5	0.236	0.29	0.29	2942	2942
	encapsulation	organic material	carbon black	1333-86-4	0.146	0.18		1821
plastics		epoxy resin	-	4.733	5.89		58888	
		inorganic material	silicondioxide	60676-86-0	43.919	54.64	60.71	546383
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10125	10125
plating	noble metal	silver	7440-22-4	0.095	0.12	0.12	1185	1185
glue	plastics	acrylic resin	-	0.175	0.22		2177	
	noble metal	silver	7440-22-4	0.620	0.77	0.99	7718	9895
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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